

# MMBT3906L, SMMBT3906L

## General Purpose Transistor

### PNP Silicon

#### Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

| Rating                            | Symbol    | Value | Unit |
|-----------------------------------|-----------|-------|------|
| Collector–Emitter Voltage         | $V_{CEO}$ | –40   | Vdc  |
| Collector–Base Voltage            | $V_{CBO}$ | –40   | Vdc  |
| Emitter–Base Voltage              | $V_{EBO}$ | –5.0  | Vdc  |
| Collector Current – Continuous    | $I_C$     | –200  | mAdc |
| Collector Current – Peak (Note 3) | $I_{CM}$  | –800  | mAdc |

#### THERMAL CHARACTERISTICS

| Characteristic  | Symbol          | Max         | Unit                       |
|---|-----------------|-------------|----------------------------|
| Total Device Dissipation FR–5 Board<br>(Note 1) @ $T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$         | $P_D$           | 225<br>1.8  | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction–to–Ambient   | $R_{\theta JA}$ | 556         | $^\circ\text{C}/\text{W}$  |
| Total Device Dissipation Alumina<br>Substrate, (Note 2) @ $T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | $P_D$           | 300<br>2.4  | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction–to–Ambient   | $R_{\theta JA}$ | 417         | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature  | $T_J, T_{stg}$  | –65 to +150 | $^\circ\text{C}$           |

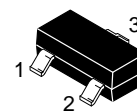
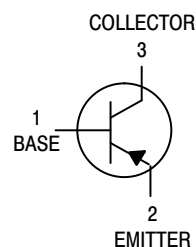
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR–5 =  $1.0 \times 0.75 \times 0.062$  in.
2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.
3. Reference SOA curve.



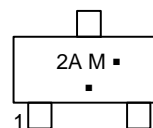
ON Semiconductor®

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SOT–23 (TO–236)  
CASE 318  
STYLE 6

#### MARKING DIAGRAM



2A = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

| Device        | Package             | Shipping†            |
|---------------|---------------------|----------------------|
| MMBT3906LT1G  | SOT–23<br>(Pb–Free) | 3,000 / Tape & Reel  |
| MMBT3906LT3G  | SOT–23<br>(Pb–Free) | 10,000 / Tape & Reel |
| SMMBT3906LT1G | SOT–23<br>(Pb–Free) | 3,000 / Tape & Reel  |
| SMMBT3906LT3G | SOT–23<br>(Pb–Free) | 10,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MMBT3906L, SMGBT3906L

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

| Characteristic  | Symbol               | Min  | Max | Unit |
|---|----------------------|------|-----|------|
| <b>OFF CHARACTERISTICS</b>  |                      |      |     |      |
| Collector–Emitter Breakdown Voltage<br>(I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0) | V <sub>(BR)CEO</sub> | -40  | -   | Vdc  |
| Collector–Base Breakdown Voltage<br>(I <sub>C</sub> = -10 μAdc, I <sub>E</sub> = 0)     | V <sub>(BR)CBO</sub> | -40  | -   | Vdc  |
| Emitter–Base Breakdown Voltage<br>(I <sub>E</sub> = -10 μAdc, I <sub>C</sub> = 0)       | V <sub>(BR)EBO</sub> | -5.0 | -   | Vdc  |
| Base Cutoff Current<br>(V <sub>CE</sub> = -30 Vdc, V <sub>EB</sub> = -3.0 Vdc)          | I <sub>BL</sub>      | -    | -50 | nAdc |
| Collector Cutoff Current<br>(V <sub>CE</sub> = -30 Vdc, V <sub>EB</sub> = -3.0 Vdc)     | I <sub>CEX</sub>     | -    | -50 | nAdc |

## ON CHARACTERISTICS (Note 4)

|   |                      |                             |                         |     |
|---|----------------------|-----------------------------|-------------------------|-----|
| DC Current Gain<br>(I <sub>C</sub> = -0.1 mAdc, V <sub>CE</sub> = -1.0 Vdc)<br>(I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -1.0 Vdc)<br>(I <sub>C</sub> = -10 mAdc, V <sub>CE</sub> = -1.0 Vdc)<br>(I <sub>C</sub> = -50 mAdc, V <sub>CE</sub> = -1.0 Vdc)<br>(I <sub>C</sub> = -100 mAdc, V <sub>CE</sub> = -1.0 Vdc) | H <sub>FE</sub>      | 60<br>80<br>100<br>60<br>30 | -<br>-<br>300<br>-<br>- | -   |
| Collector–Emitter Saturation Voltage<br>(I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = -1.0 mAdc)<br>(I <sub>C</sub> = -50 mAdc, I <sub>B</sub> = -5.0 mAdc)  | V <sub>CE(sat)</sub> | -<br>-                      | -0.25<br>-0.4           | Vdc |
| Base–Emitter Saturation Voltage<br>(I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = -1.0 mAdc)<br>(I <sub>C</sub> = -50 mAdc, I <sub>B</sub> = -5.0 mAdc)   | V <sub>BE(sat)</sub> | -0.65<br>-                  | -0.85<br>-0.95          | Vdc |

## SMALL–SIGNAL CHARACTERISTICS

|  |                  |     |     |                    |
|--|------------------|-----|-----|--------------------|
| Current–Gain – Bandwidth Product<br>(I <sub>C</sub> = -10 mAdc, V <sub>CE</sub> = -20 Vdc, f = 100 MHz)        | f <sub>T</sub>   | 250 | -   | MHz                |
| Output Capacitance<br>(V <sub>CB</sub> = -5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)                            | C <sub>obo</sub> | -   | 4.5 | pF                 |
| Input Capacitance<br>(V <sub>EB</sub> = -0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)                             | C <sub>ibo</sub> | -   | 10  | pF                 |
| Input Impedance<br>(I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -10 Vdc, f = 1.0 kHz)                        | h <sub>ie</sub>  | 2.0 | 12  | kΩ                 |
| Voltage Feedback Ratio<br>(I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -10 Vdc, f = 1.0 kHz)                 | h <sub>re</sub>  | 0.1 | 10  | X 10 <sup>-4</sup> |
| Small–Signal Current Gain<br>(I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -10 Vdc, f = 1.0 kHz)              | h <sub>fe</sub>  | 100 | 400 | -                  |
| Output Admittance<br>(I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -10 Vdc, f = 1.0 kHz)                      | h <sub>oe</sub>  | 3.0 | 60  | μmhos              |
| Noise Figure<br>(I <sub>C</sub> = -100 μAdc, V <sub>CE</sub> = -5.0 Vdc, R <sub>S</sub> = 1.0 kΩ, f = 1.0 kHz) | NF               | -   | 4.0 | dB                 |

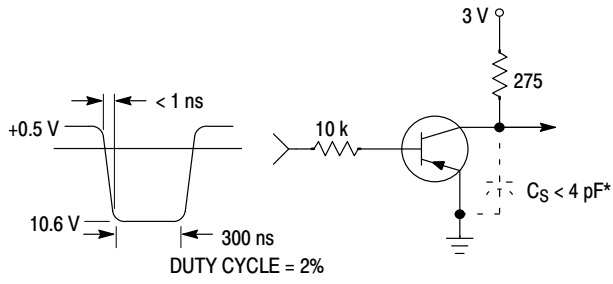
## SWITCHING CHARACTERISTICS

|              |  |                |   |     |    |
|--------------|--|----------------|---|-----|----|
| Delay Time   | (V <sub>CC</sub> = -3.0 Vdc, V <sub>BE</sub> = 0.5 Vdc,<br>I <sub>C</sub> = -10 mAdc, I <sub>B1</sub> = -1.0 mAdc) | t <sub>d</sub> | - | 35  | ns |
| Rise Time    |  | t <sub>r</sub> | - | 35  |    |
| Storage Time | (V <sub>CC</sub> = -3.0 Vdc, I <sub>C</sub> = -10 mAdc,<br>I <sub>B1</sub> = I <sub>B2</sub> = -1.0 mAdc)          | t <sub>s</sub> | - | 225 | ns |
| Fall Time    |  | t <sub>f</sub> | - | 75  |    |

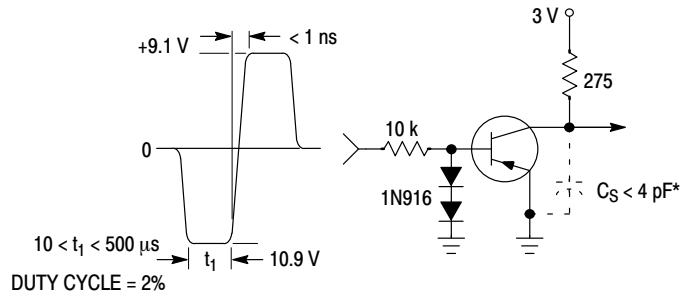
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

# MMBT3906L, SMMBT3906L



**Figure 1. Delay and Rise Time Equivalent Test Circuit**

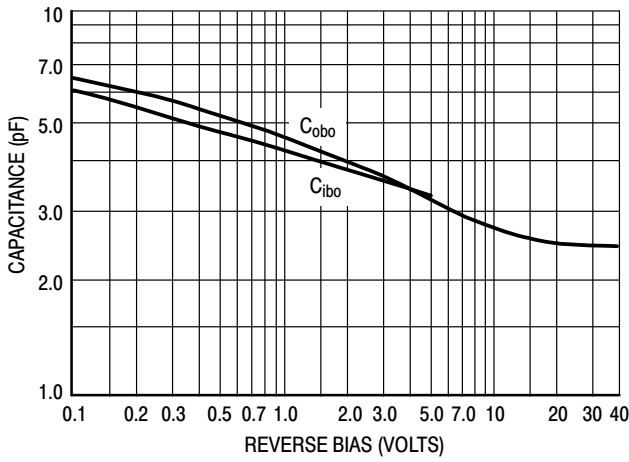


**Figure 2. Storage and Fall Time Equivalent Test Circuit**

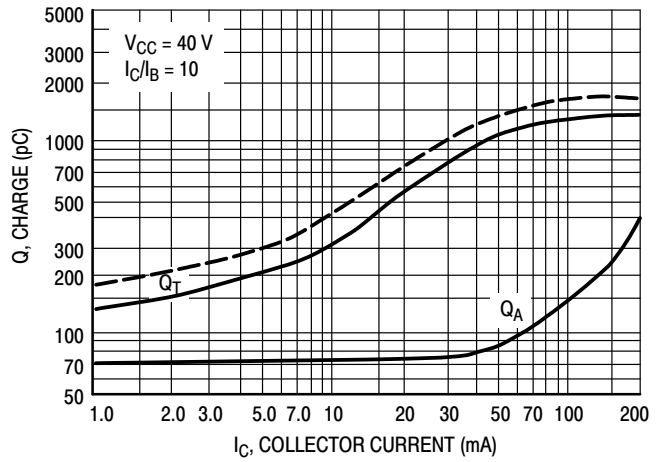
\* Total shunt capacitance of test jig and connectors

## TYPICAL TRANSIENT CHARACTERISTICS

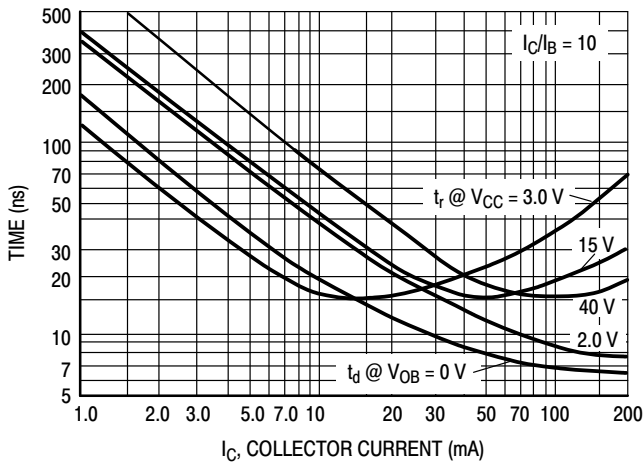
—  $T_J = 25^\circ\text{C}$   
 - - -  $T_J = 125^\circ\text{C}$



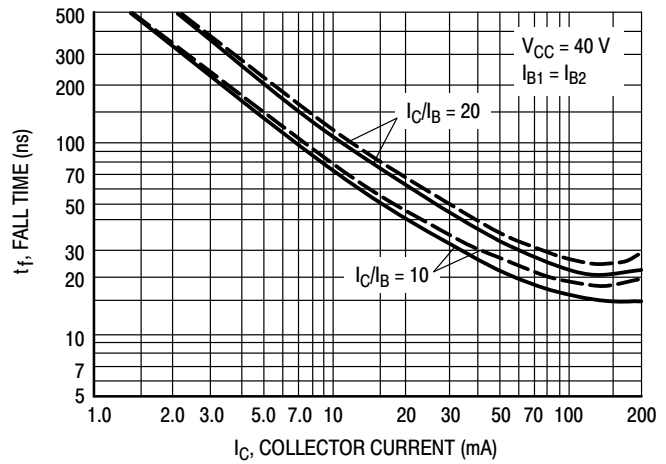
**Figure 3. Capacitance**



**Figure 4. Charge Data**



**Figure 5. Turn-On Time**



**Figure 6. Fall Time**

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## TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

( $V_{CE} = -5.0$  Vdc,  $T_A = 25^\circ\text{C}$ , Bandwidth = 1.0 Hz)

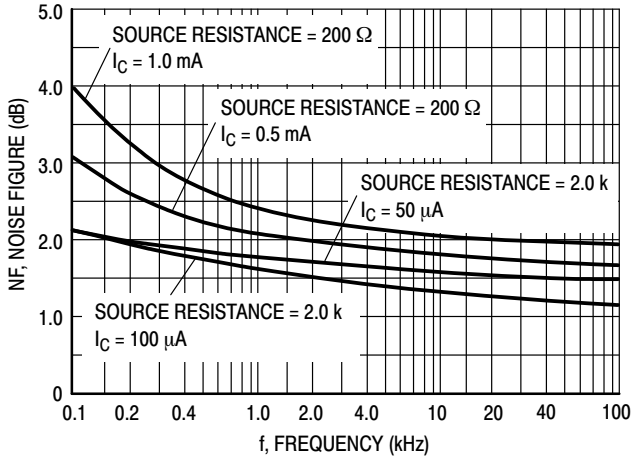


Figure 7.

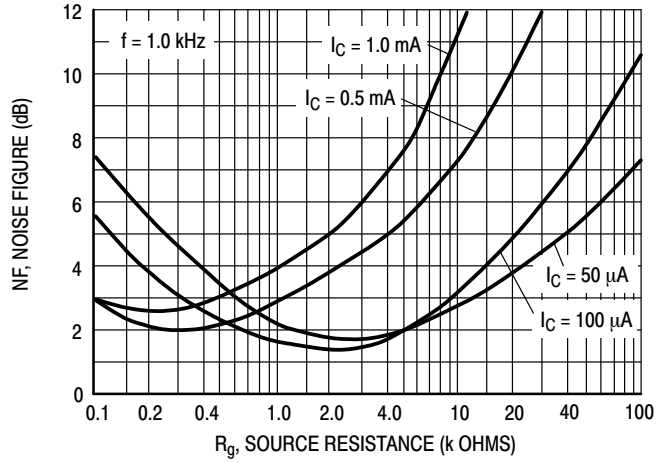


Figure 8.

## h PARAMETERS

( $V_{CE} = -10$  Vdc,  $f = 1.0$  kHz,  $T_A = 25^\circ\text{C}$ )

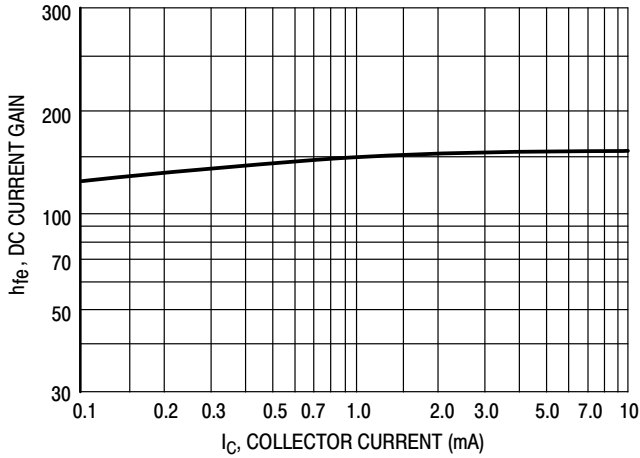


Figure 9. Current Gain

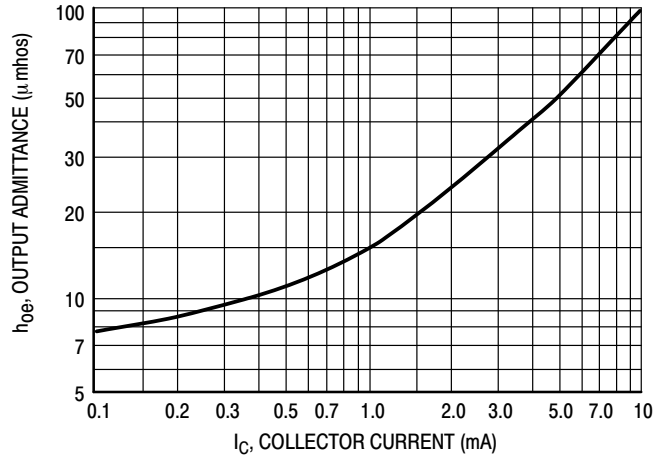


Figure 10. Output Admittance

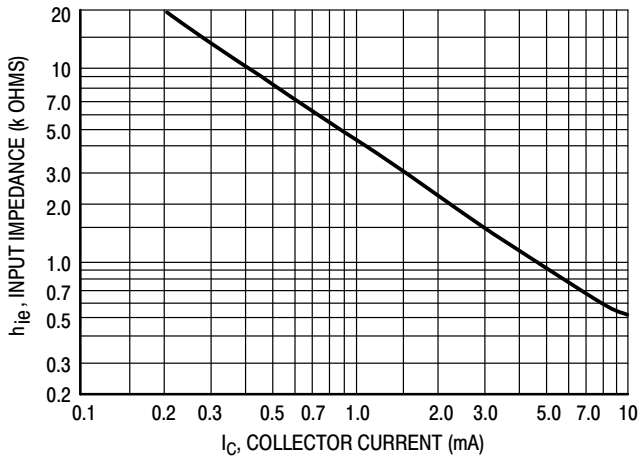


Figure 11. Input Impedance

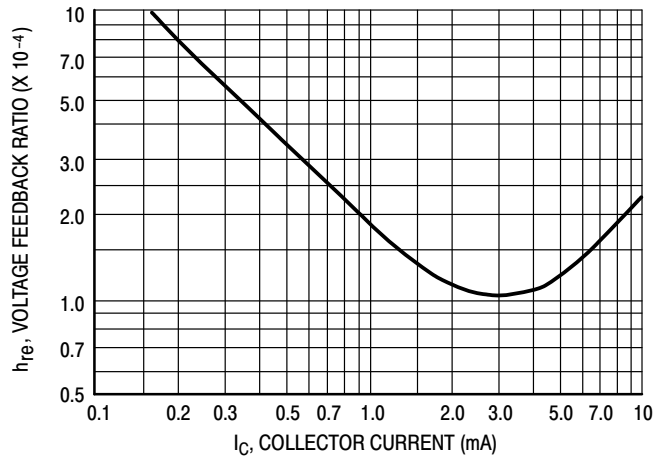


Figure 12. Voltage Feedback Ratio

# MMBT3906L, SMMBT3906L

## TYPICAL STATIC CHARACTERISTICS

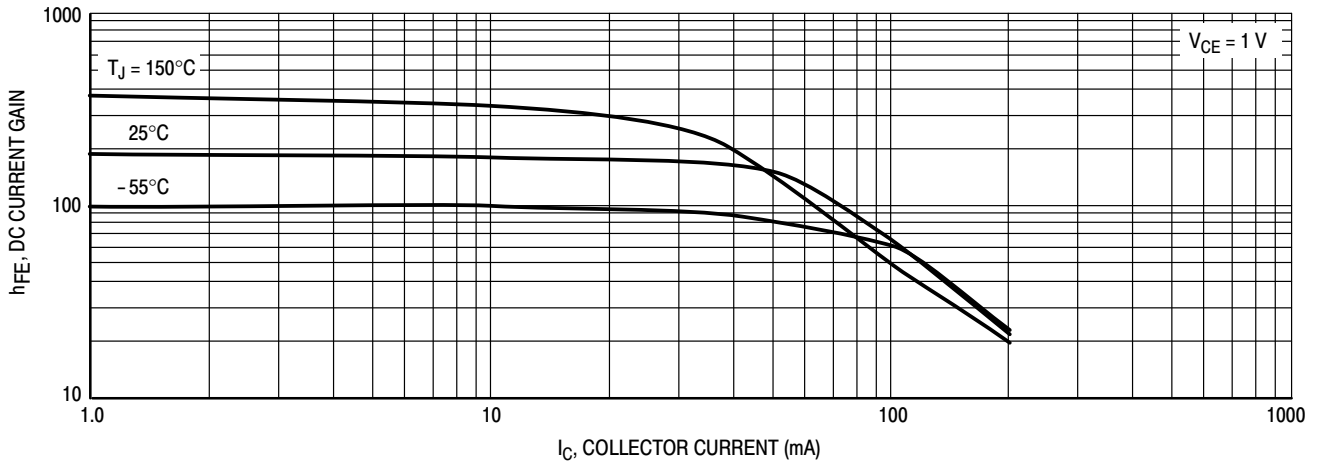


Figure 13. DC Current Gain

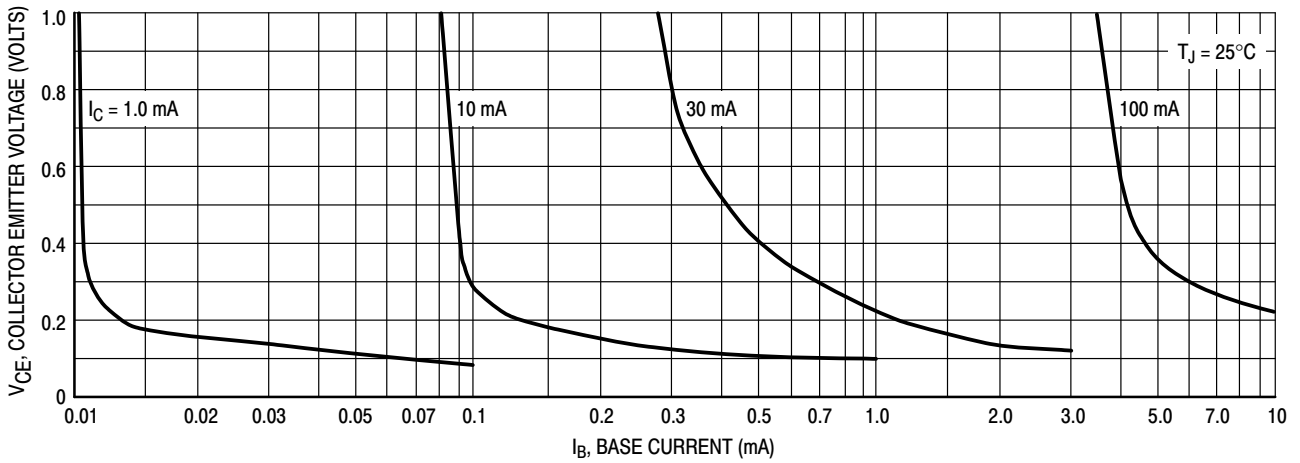
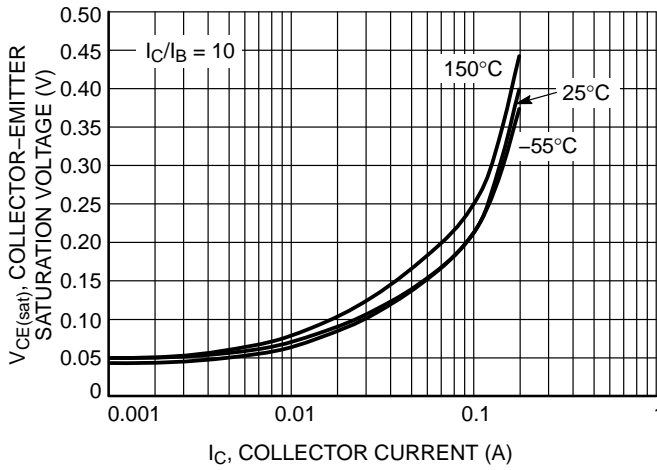
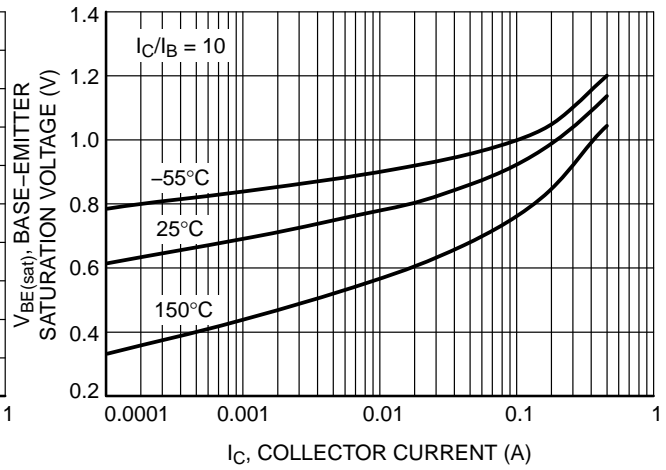


Figure 14. Collector Saturation Region

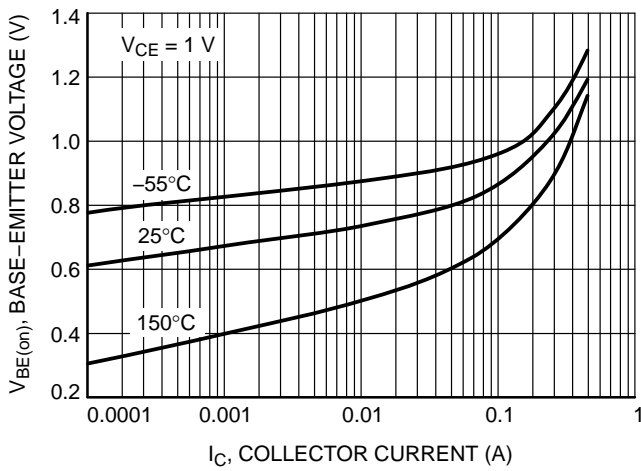
# MMBT3906L, SMMBT3906L



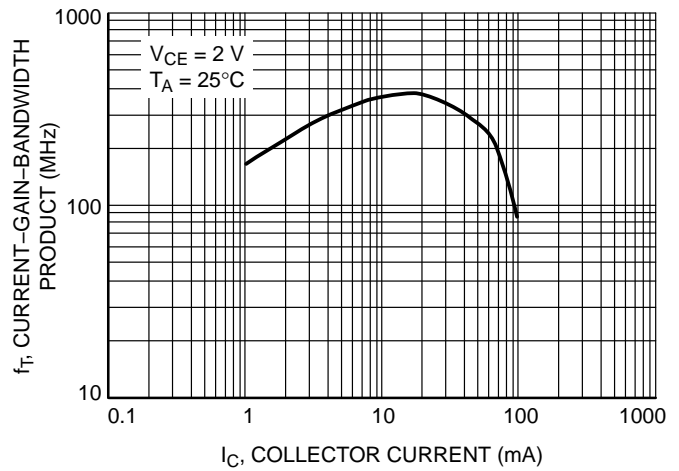
**Figure 15. Collector Emitter Saturation Voltage vs. Collector Current**



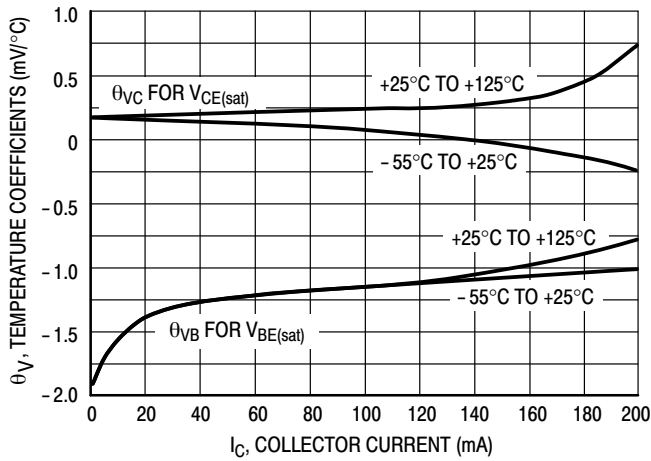
**Figure 16. Base Emitter Saturation Voltage vs. Collector Current**



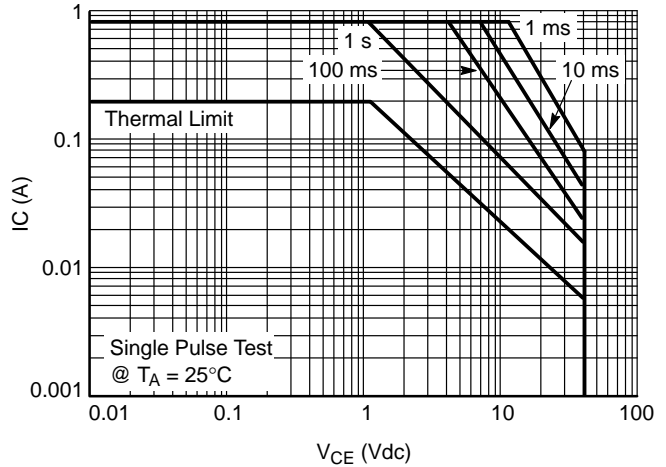
**Figure 17. Base Emitter Voltage vs. Collector Current**



**Figure 18. Current Gain Bandwidth vs. Collector Current**



**Figure 19. Temperature Coefficients**



**Figure 20. Safe Operating Area**

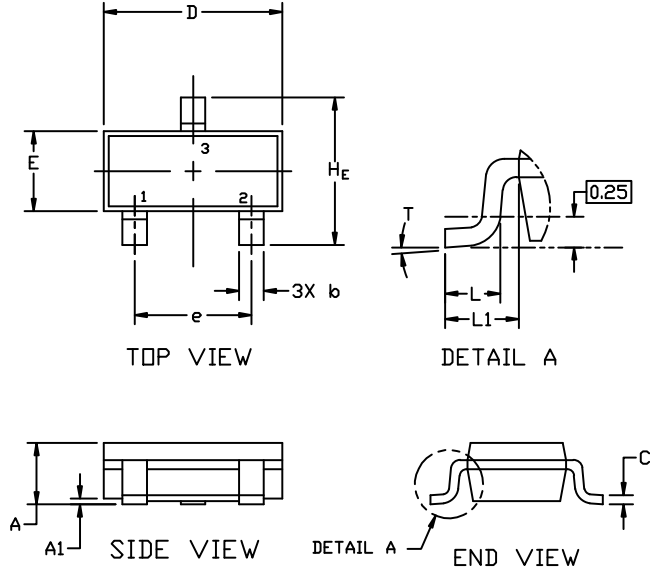
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**SOT-23 (TO-236)**  
CASE 318  
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM            | MILLIMETERS |      |      | INCHES |       |       |
|----------------|-------------|------|------|--------|-------|-------|
|                | MIN.        | NOM. | MAX. | MIN.   | NOM.  | MAX.  |
| A              | 0.89        | 1.00 | 1.11 | 0.035  | 0.039 | 0.044 |
| A1             | 0.01        | 0.06 | 0.10 | 0.000  | 0.002 | 0.004 |
| b              | 0.37        | 0.44 | 0.50 | 0.015  | 0.017 | 0.020 |
| c              | 0.08        | 0.14 | 0.20 | 0.003  | 0.006 | 0.008 |
| D              | 2.80        | 2.90 | 3.04 | 0.110  | 0.114 | 0.120 |
| E              | 1.20        | 1.30 | 1.40 | 0.047  | 0.051 | 0.055 |
| e              | 1.78        | 1.90 | 2.04 | 0.070  | 0.075 | 0.080 |
| L              | 0.30        | 0.43 | 0.55 | 0.012  | 0.017 | 0.022 |
| L1             | 0.35        | 0.54 | 0.69 | 0.014  | 0.021 | 0.027 |
| H <sub>E</sub> | 2.10        | 2.40 | 2.64 | 0.083  | 0.094 | 0.104 |
| T              | 0°          | ---  | 10°  | 0°     | ---   | 10°   |

**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



**RECOMMENDED MOUNTING FOOTPRINT**

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

|                         |                        |  |
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**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**



**SOT-23 (TO-236)**  
**CASE 318**  
**ISSUE AT**

DATE 01 MAR 2023

- |   |   |   |   |   |   |
|---|---|---|---|---|---|
| STYLE 1 THRU 5:<br>CANCELLED                            | STYLE 6:<br>PIN 1. BASE<br>2. EMITTER<br>3. COLLECTOR | STYLE 7:<br>PIN 1. EMITTER<br>2. BASE<br>3. COLLECTOR       | STYLE 8:<br>PIN 1. ANODE<br>2. NO CONNECTION<br>3. CATHODE  |   |   |
| STYLE 9:<br>PIN 1. ANODE<br>2. ANODE<br>3. CATHODE      | STYLE 10:<br>PIN 1. DRAIN<br>2. SOURCE<br>3. GATE     | STYLE 11:<br>PIN 1. ANODE<br>2. CATHODE<br>3. CATHODE-ANODE | STYLE 12:<br>PIN 1. CATHODE<br>2. CATHODE<br>3. ANODE       | STYLE 13:<br>PIN 1. SOURCE<br>2. DRAIN<br>3. GATE           | STYLE 14:<br>PIN 1. CATHODE<br>2. GATE<br>3. ANODE          |
| STYLE 15:<br>PIN 1. GATE<br>2. CATHODE<br>3. ANODE      | STYLE 16:<br>PIN 1. ANODE<br>2. CATHODE<br>3. CATHODE | STYLE 17:<br>PIN 1. NO CONNECTION<br>2. ANODE<br>3. CATHODE | STYLE 18:<br>PIN 1. NO CONNECTION<br>2. CATHODE<br>3. ANODE | STYLE 19:<br>PIN 1. CATHODE<br>2. ANODE<br>3. CATHODE-ANODE | STYLE 20:<br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE          |
| STYLE 21:<br>PIN 1. GATE<br>2. SOURCE<br>3. DRAIN       | STYLE 22:<br>PIN 1. RETURN<br>2. OUTPUT<br>3. INPUT   | STYLE 23:<br>PIN 1. ANODE<br>2. ANODE<br>3. CATHODE         | STYLE 24:<br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE           | STYLE 25:<br>PIN 1. ANODE<br>2. CATHODE<br>3. GATE          | STYLE 26:<br>PIN 1. CATHODE<br>2. ANODE<br>3. NO CONNECTION |
| STYLE 27:<br>PIN 1. CATHODE<br>2. CATHODE<br>3. CATHODE | STYLE 28:<br>PIN 1. ANODE<br>2. ANODE<br>3. ANODE     |   |   |   |   |

|                         |                        |   |
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